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> Customer No.: 31561 Application No.: 10/604,692

Docket No.: 10156-US-PA

AMENDMENTS

To the Claims:

1. (currently amended) A split-gate non-volatile memory cell, comprising:

a substrate;

a charge-trapping layer on the substrate;

a split gate on the charge-trapping layer, including at least one split region directly

over the charge-trapping layer, wherein the split gate-is-composed-of comprises at least

two separated conductive pieces and the conductive pieces that are electrically connected

to a common voltage source shorted with each other and are arranged adjacently to form

the at least one split region without any other conductor in the at least one split region; and

a source/drain in the substrate beside the split gate, wherein

the charge-trapping layer around the split region serves as a coding region.

Claim 2-3: (canceled).

4. (previously presented) The split-gate non-volatile memory cell of claim 1,

wherein the conductive pieces of the split gate include a pair of conductive spacers and a

conductive layer between the pair of conductive spacers.

5. (original) The split-gate non-volatile memory cell of claim 4, wherein the pair of

conductive spacers are arranged with two substantially vertical sidewalls thereof adjacent

to the source/drain.

6. (original) The split-gate non-volatile memory cell of claim 5, further comprising

an insulator on the source/drain, wherein the pair of conductive spacers are disposed on

the sidewalls of the insulator.

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Claim 7: (canceled).

8. (previously presented) The split-gate non-volatile memory cell of claim 1,

wherein the conductive pieces are separated from each other by a dielectric layer.

9. (original) The split-gate non-volatile memory cell of claim 1, wherein the split

gate comprises polysilicon.

10. (original) The split-gate non-volatile memory cell of claim 1, wherein the

charge-trapping layer comprises a silicon nitride layer disposed between two silicon oxide

layers.

11. (original) The split-gate non-volatile memory cell of claim 1, wherein the

charge-trapping layer comprises aluminum oxide (Al₂O₃).

12. (original) The split-gate non-volatile memory cell of claim 1, wherein the

substrate comprises a p-substrate, and the source/drain comprises an n-type source/drain.

Claims 13-34: (canceled).

35. (currently amended) An operating method of a split-gate non-volatile memory

cell, wherein

the split-gate non-volatile memory cell comprises:

a substrate;

a charge-trapping layer on the substrate;

a split gate on the charge-trapping layer, including at least one split region directly

over the charge-trapping layer, wherein the charge-trapping layer around the split region

serves as a coding region, the split gate-is composed of comprises at least two separated

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conductive pieces and the conductive pieces that are electrically connected to a common voltage source shorted with each other and are arranged adjacently to form the at least one split region without any other conductor in the at least one split region; and

a source/drain in the substrate beside the split gate, and

the operating method comprises:

in a programming operation:

applying 0V to the substrate and the source/drain; and

applying a first negative voltage to the split gate, the first negative voltage being sufficiently high for injecting electrons into the coding region; and

in an erasing operation:

applying 0V to the split gate, wherein each conductive piece is at an electric state of 0 V;

floating the source/drain; and

applying a second negative voltage to the substrate, the second positive voltage being sufficiently high for ejecting electrons from the coding region.

- 36. (original) The operating method of claim 35, wherein the first negative voltage is about -10V.
- 37. (original) The operating method of claim 35, wherein the second negative voltage is about -10V.

Claims 38-45: (canceled).